

STM32H7xxXx-Disco

MB1381

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TOP.SchDoc

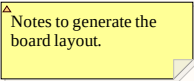


Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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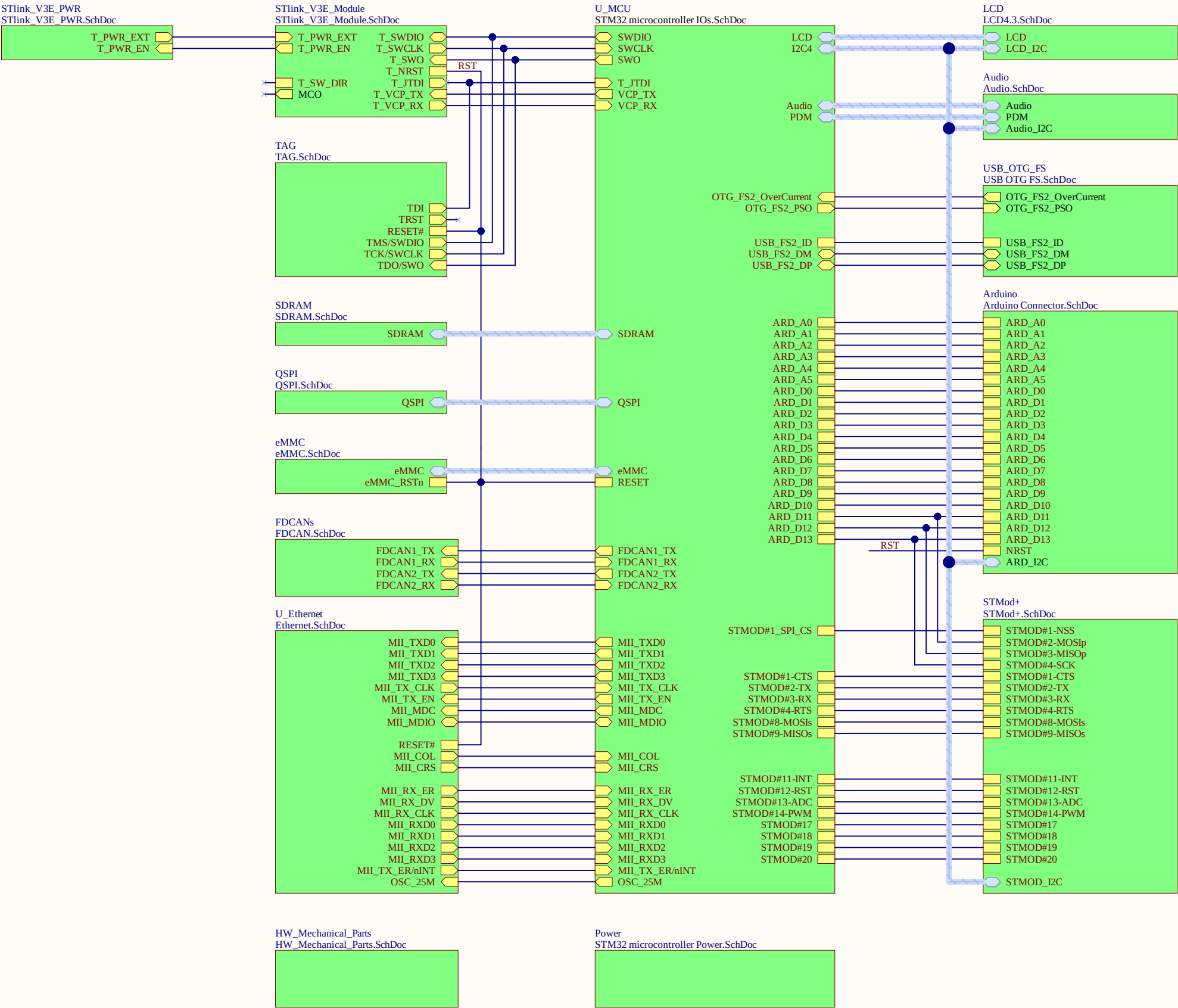
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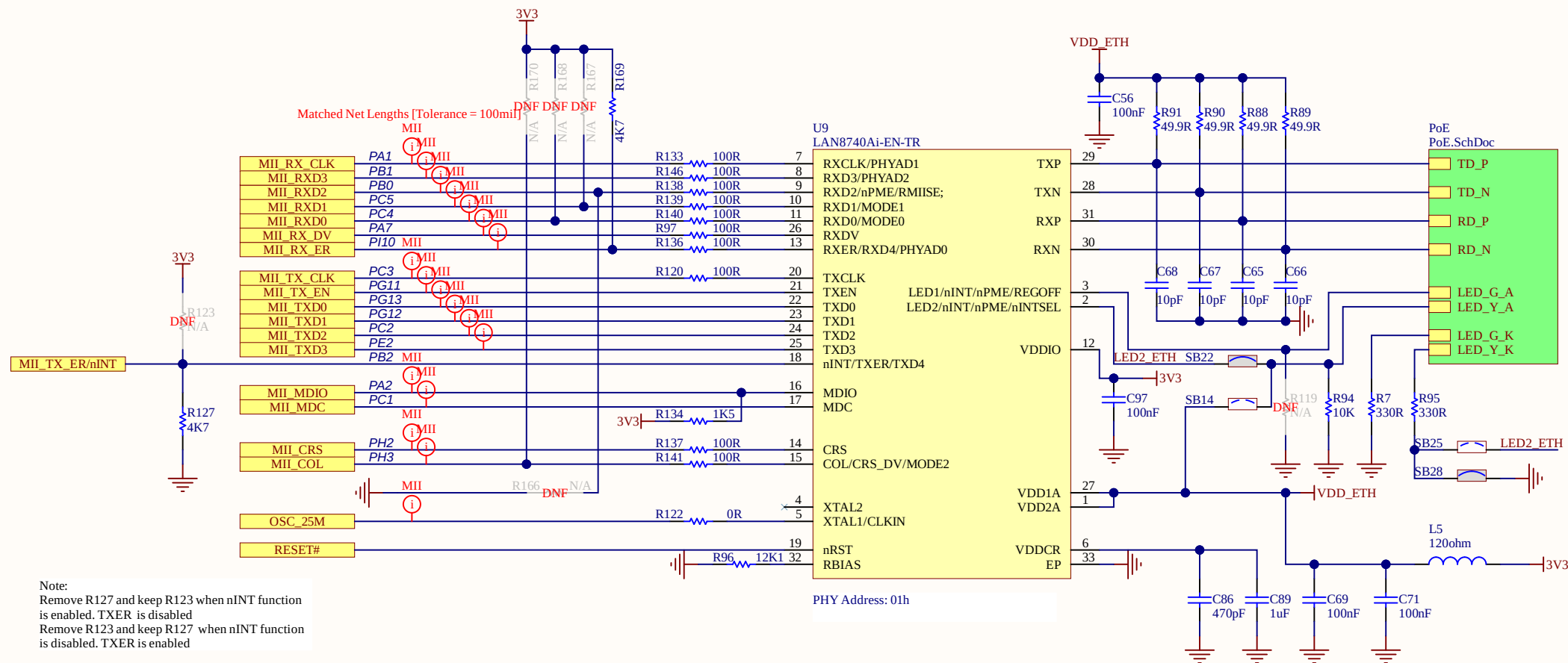
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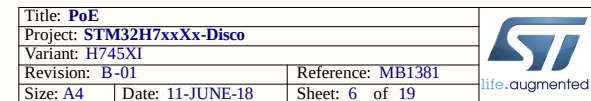
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Project: STM32H7xxXx-Disco		
Variant: H745XI		
Revision: B-01		Reference: MB1381
Size: A4	Date: 11-JUNE-18	Sheet: 1 of 19

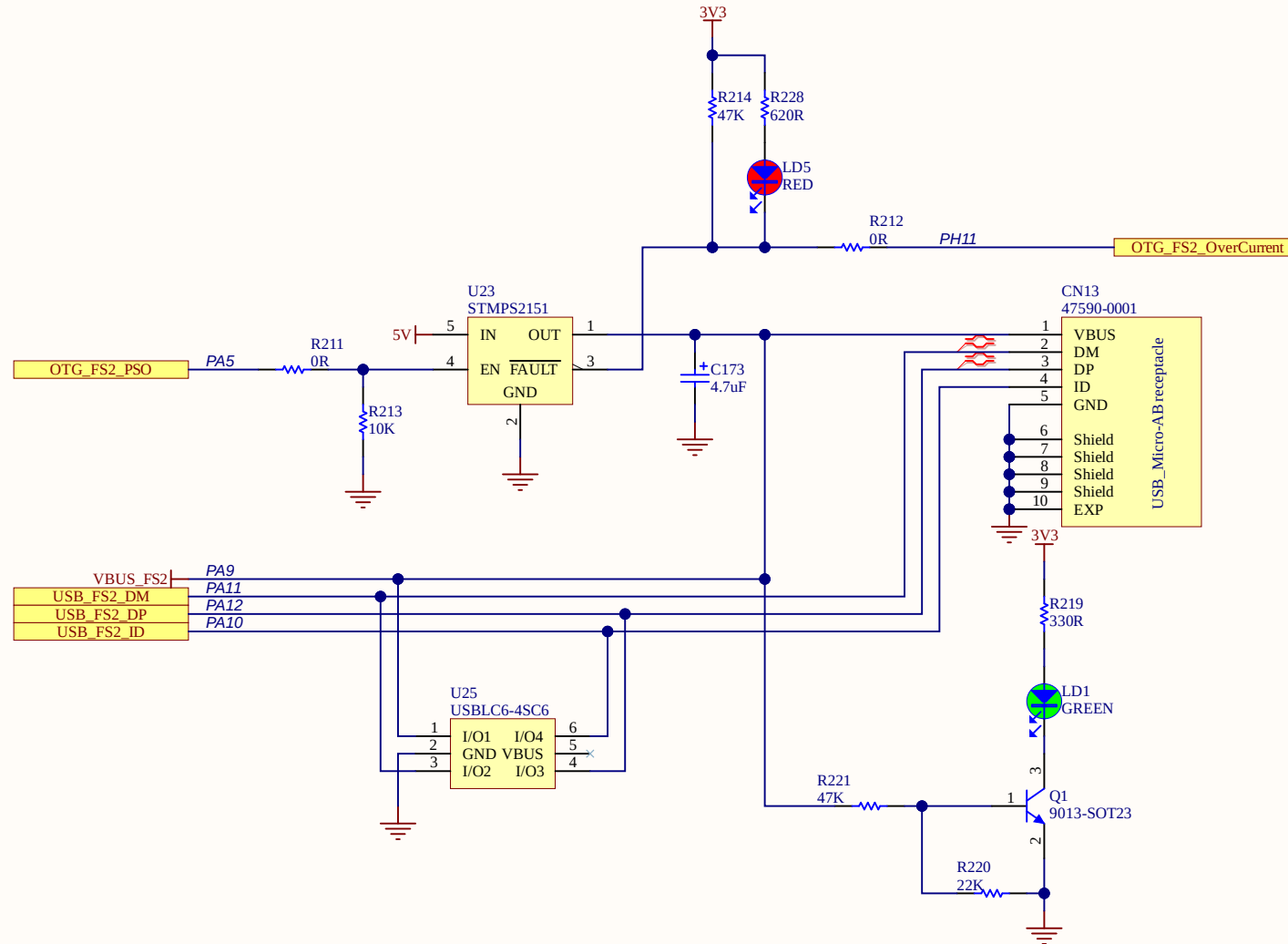






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KRJ-CB4.2GYZNL





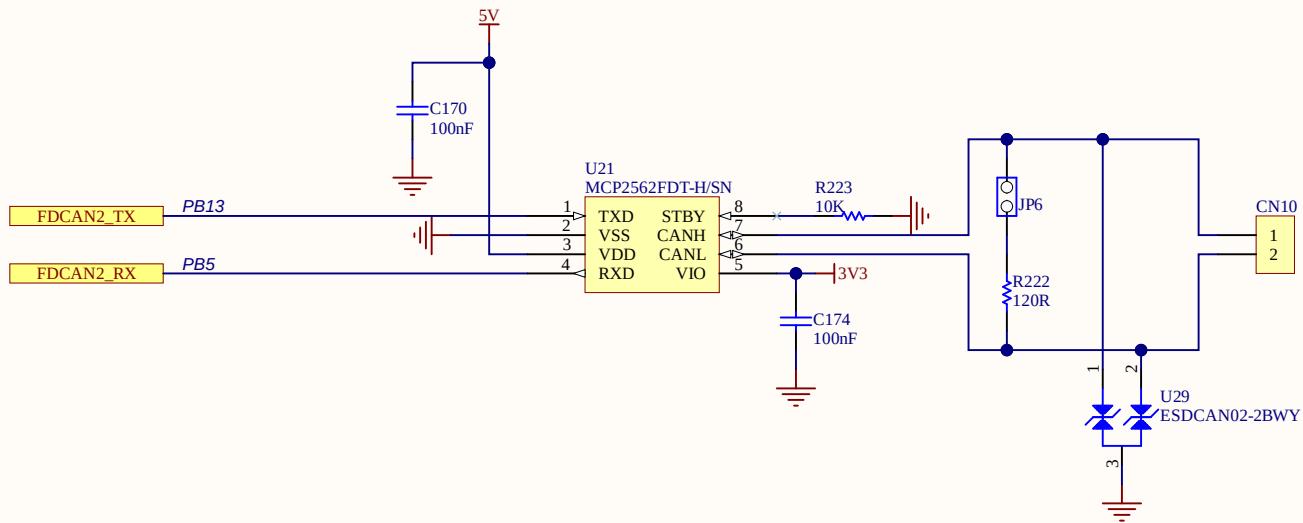
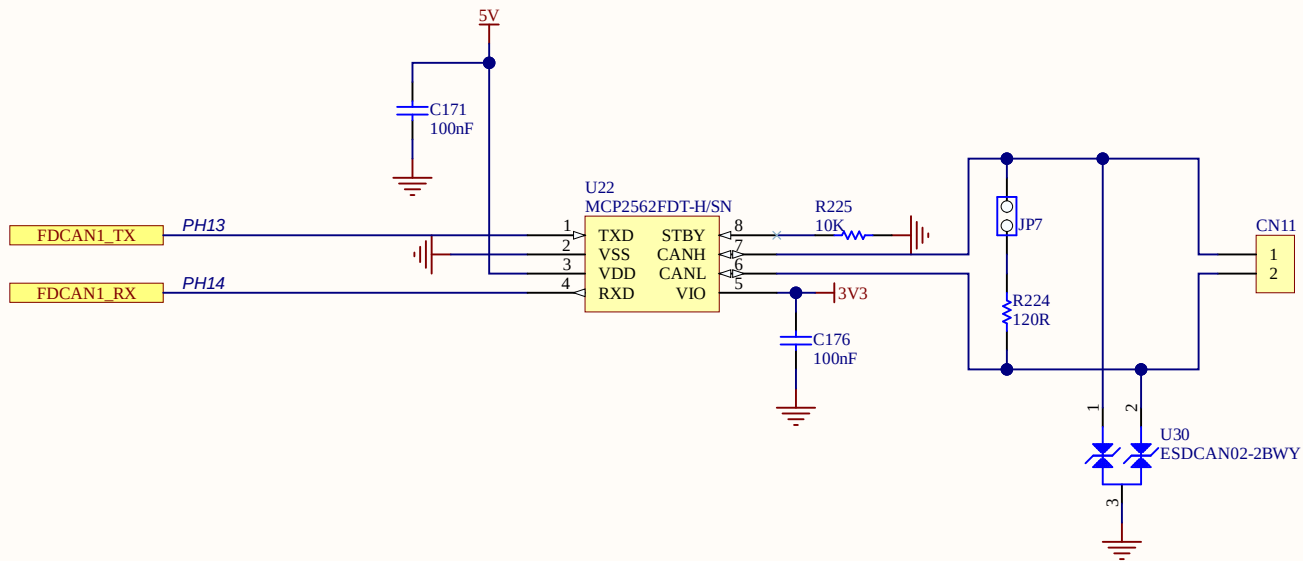
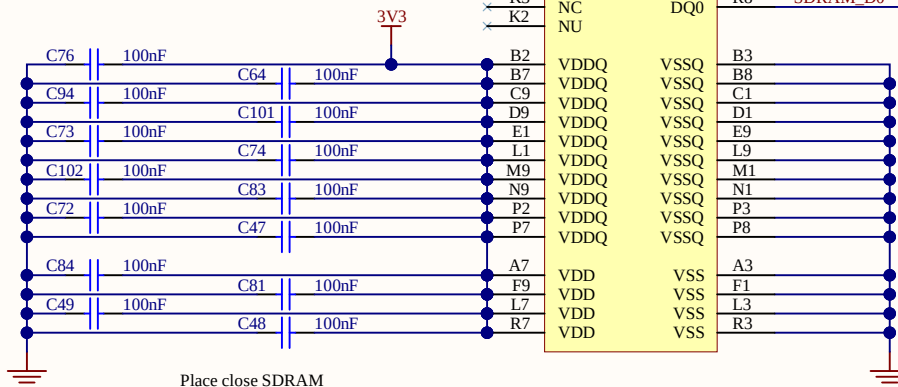
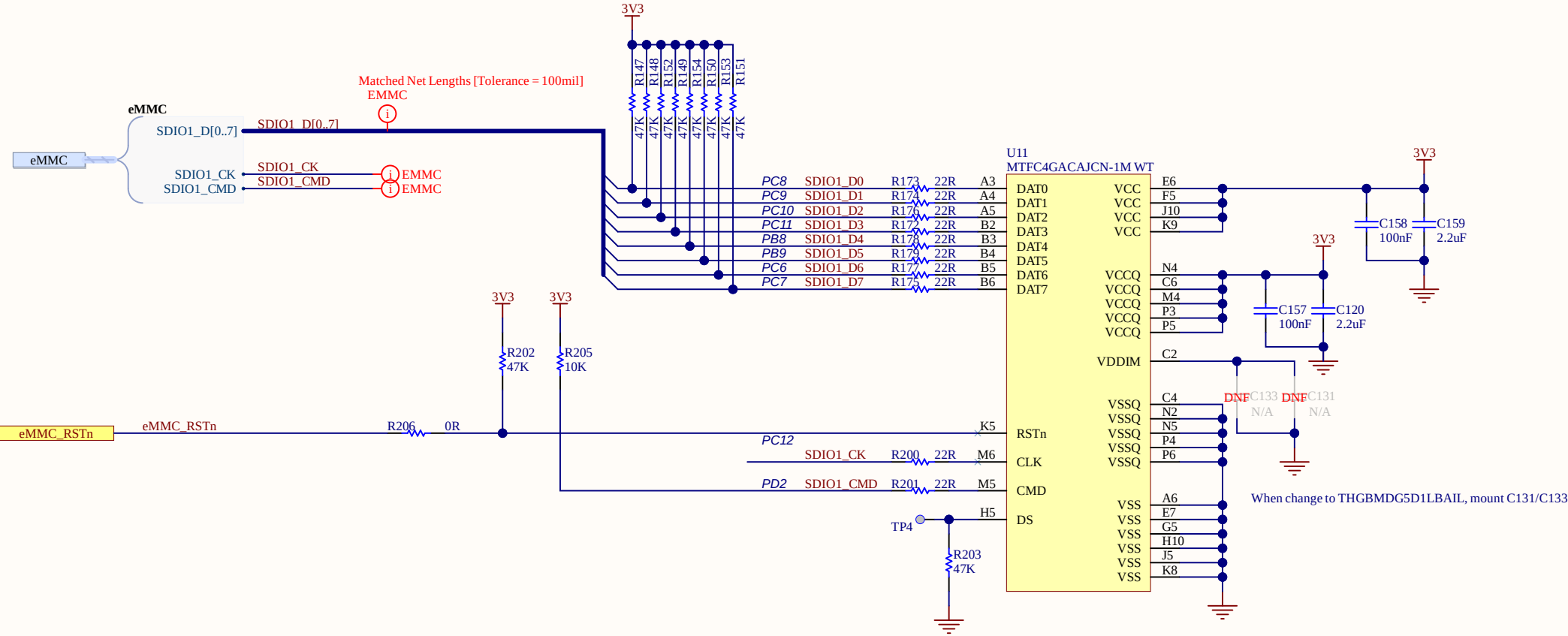
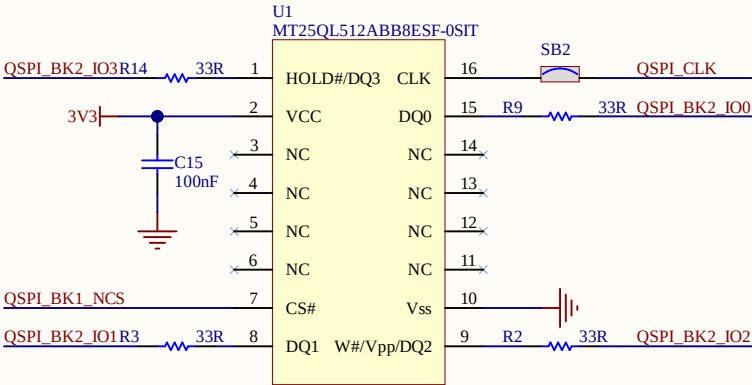
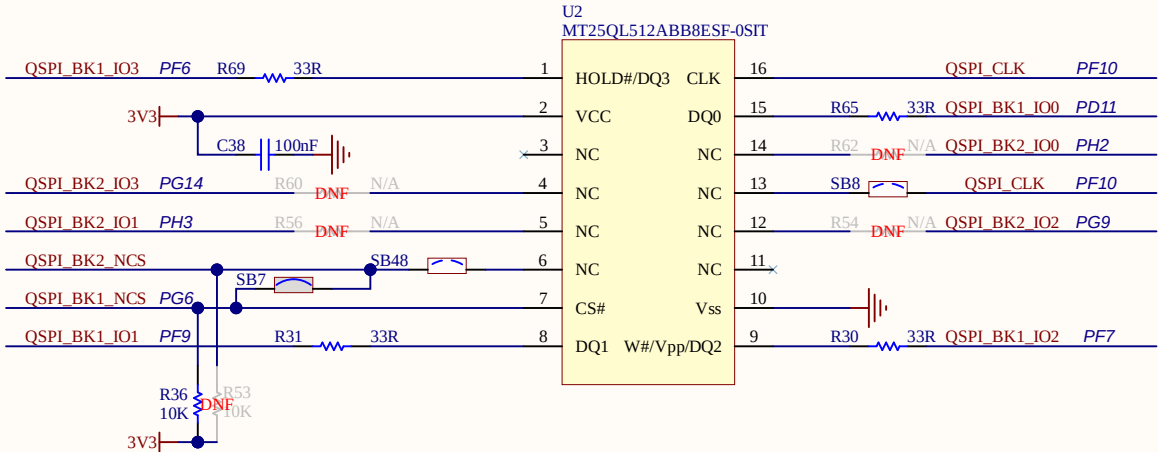
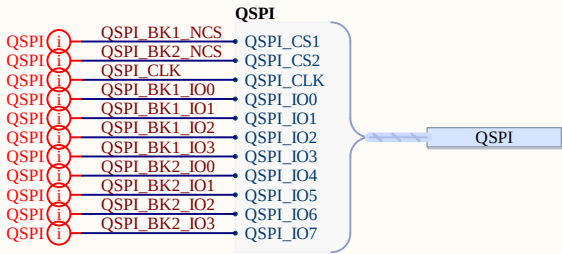


Diagram illustrating the connections for SDRAM banks. The diagram shows a central vertical bus connected to six SDRAM banks. The top bank is labeled "SDRAM" and has connections for address (A[0..11], D[0..15]), data (BA0, BA1, NBL0, NBL1), and control (SDNE1, SDCKE1, SDNCAS, SDNRAS, SDNWE, SDCLK). The bottom five banks are labeled "SDRAM" and have connections for address (A[0..11], D[0..15]), data (BA0, BA1, NBL0, NBL1), and control (SDNE1, SDCKE1, SDNCAS, SDNRAS, SDNWE, SDCLK).





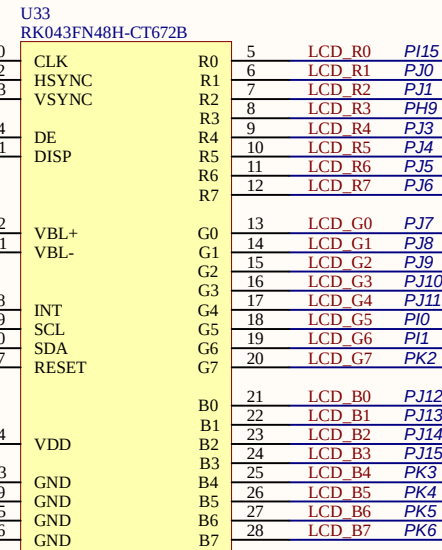
Matched Net Lengths [Tolerance = 100mil]



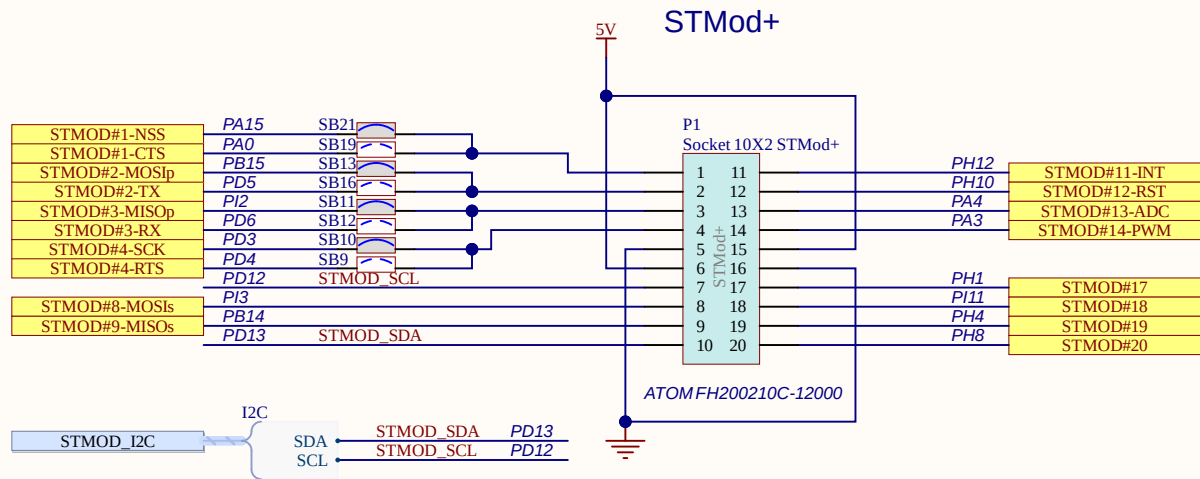
Twin Quad SPI Flash solutions:

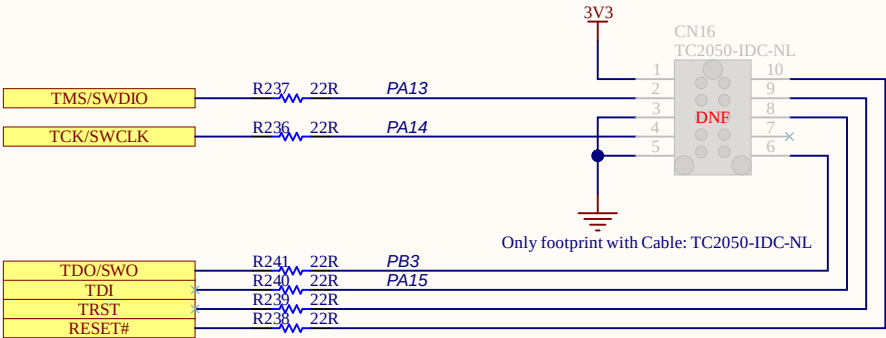
One Twin Quad SPI Fillash	U2:MT25TL01GHBB8ESF-0SIT	U1:NA	R53/R62/R54/R56/R60/SB8/SB48 ON	R14/R3/R2/R9/SB2/C15 OFF
Two Quad SPI Fillash	U1:MT25QL512ABB8ESF-0SIT	U2:MT25QL512ABB8ESF-0SIT	R14/R3/R2/R9/SB2/C15 ON	R53/R62/R54/R56/R60/SB8/SB48 OFF

LCD

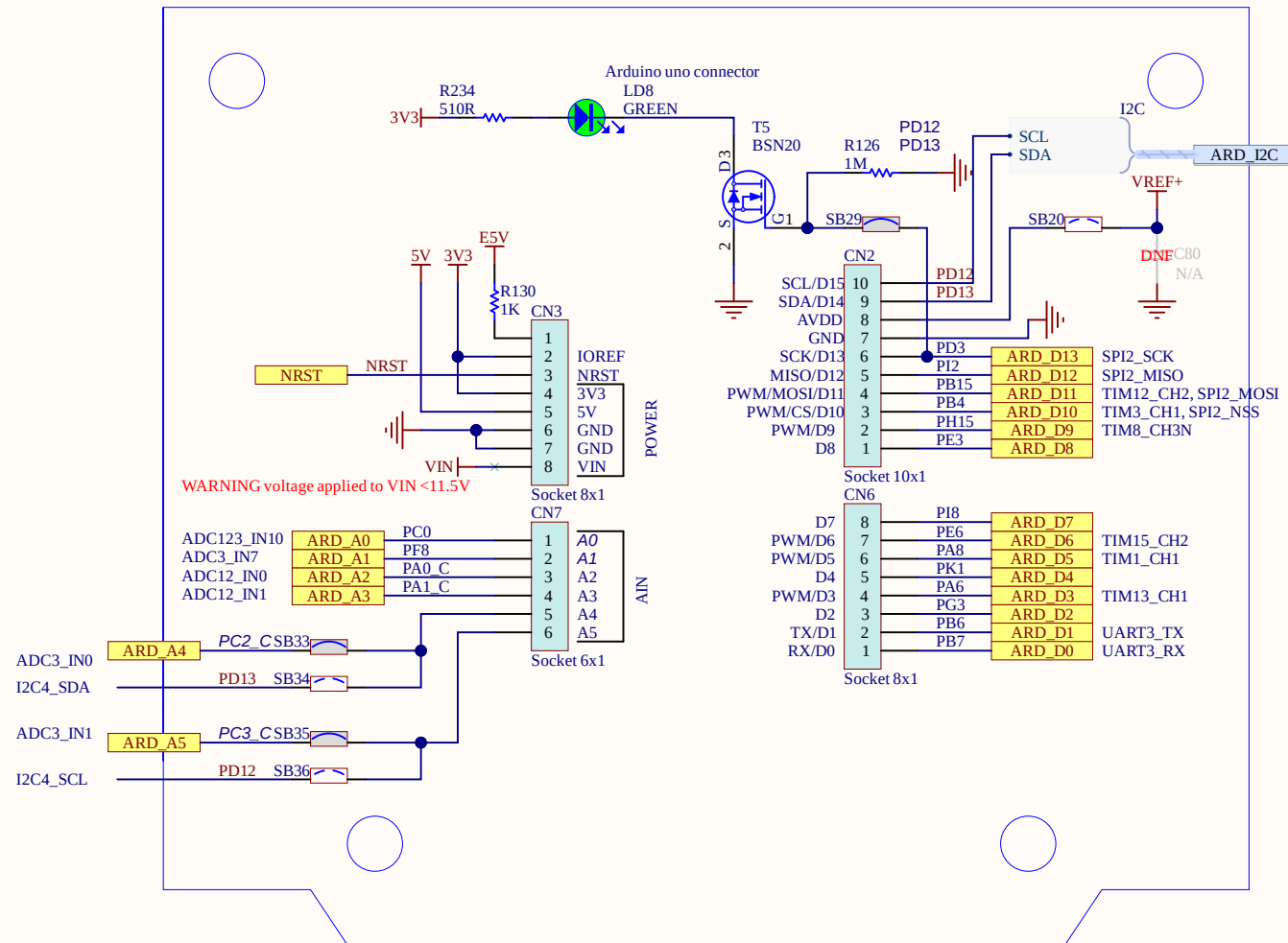


Backlight driver & PFC of LCD panel

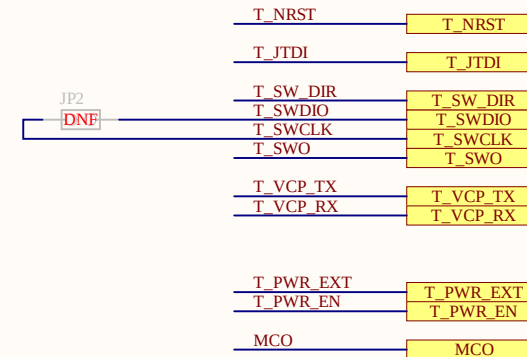
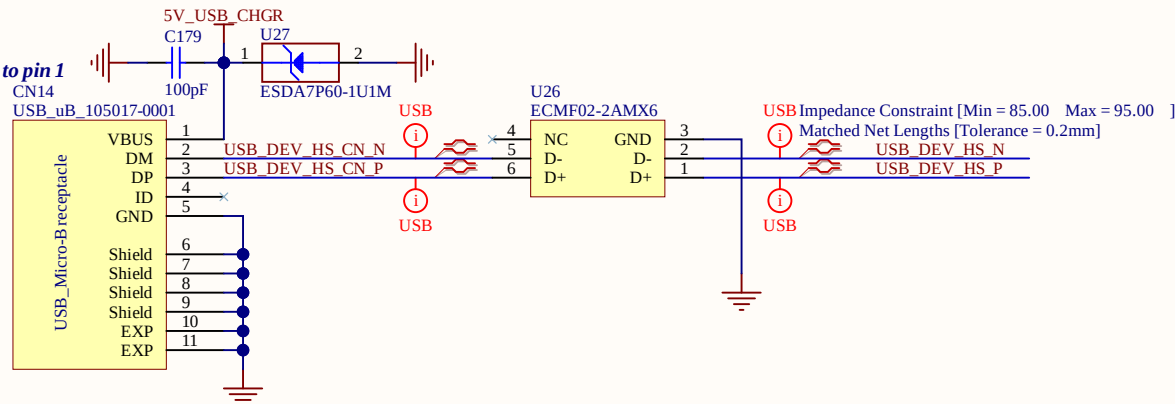




Place this connector close to STDC, they will share the same ESD components

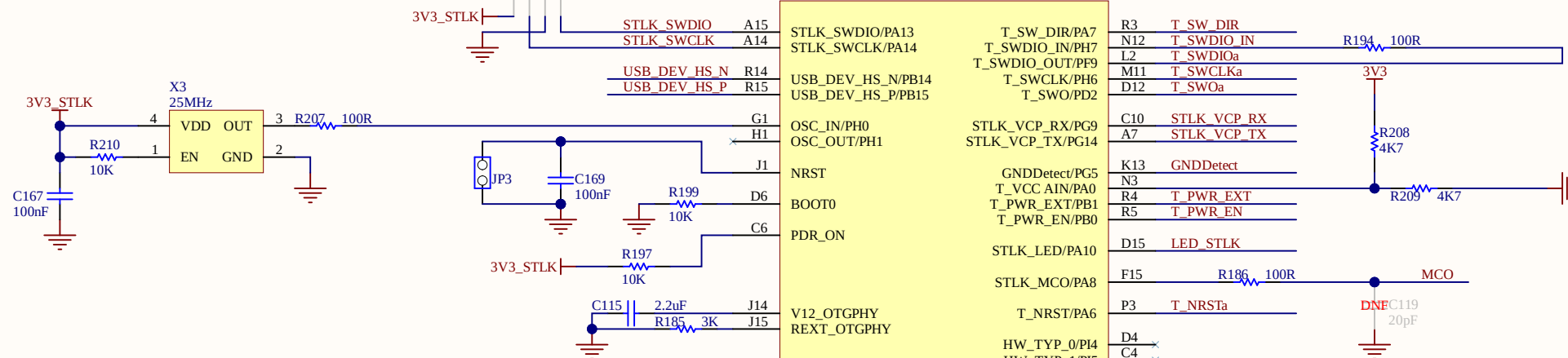


Capacitor Close to pin 1



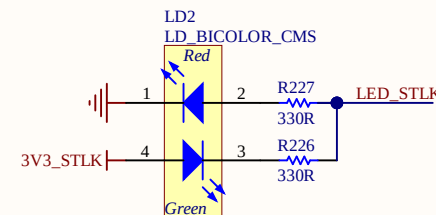
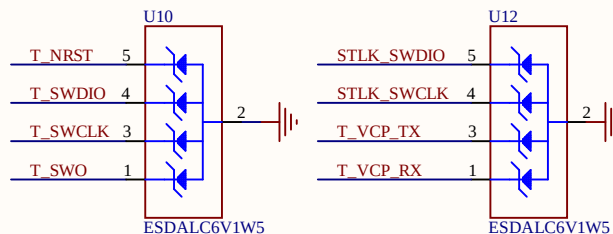
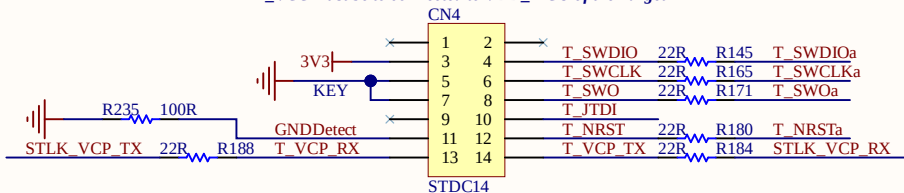
Must be on a border or the PCB.

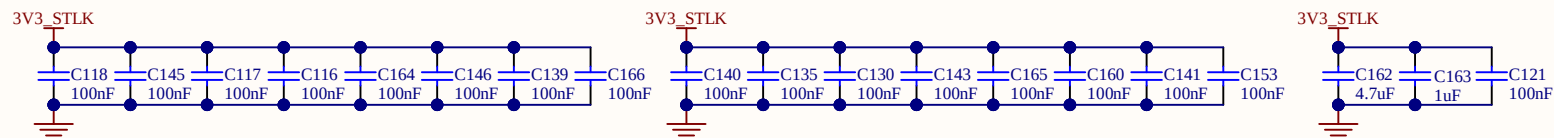
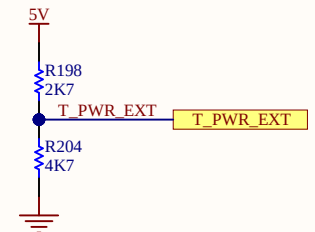
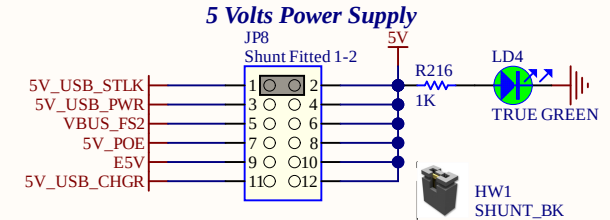
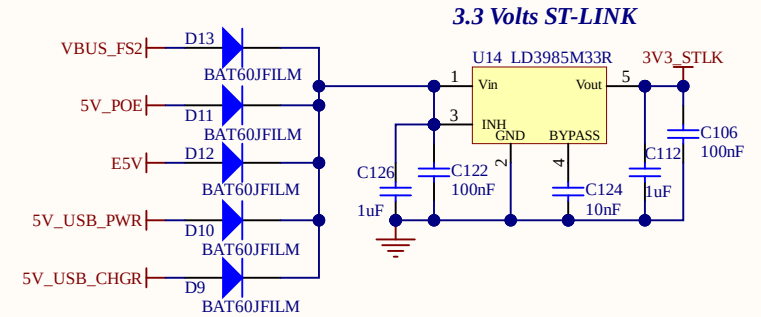
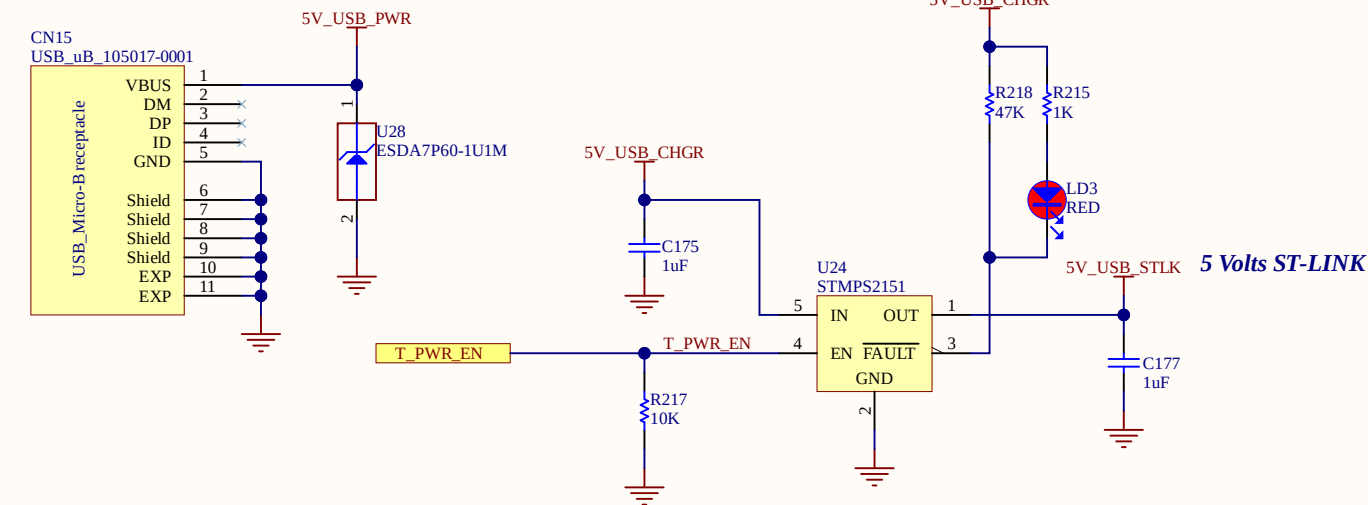
Silkscreen = Reserved



STDC14 Receiver

T_VCC must be connected to VDD_MCU of the Target





HW Mechanical parts

HW6
MB1381A

PCB

HW7
MB1381A-01 XXXX

BOARD REF

HW8
STM32H745I-Disco

BOARD CPN

HW4

LOGO ST

HW5

LOGO CE

HW3

LOGO ESD

HW9

LOGO ROHS

HW10

LOGO STM32

